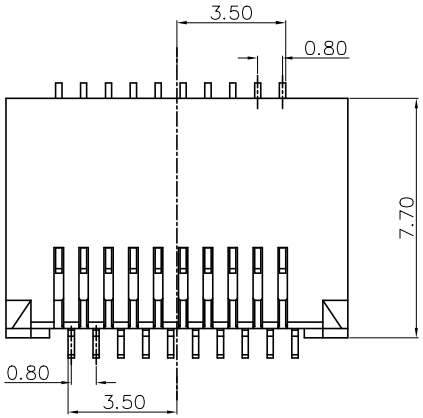
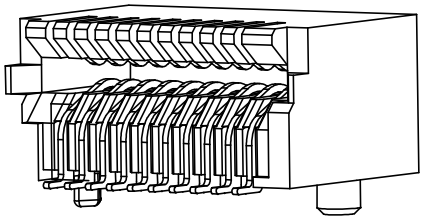
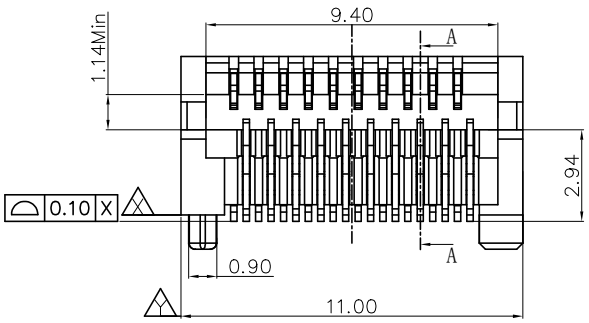
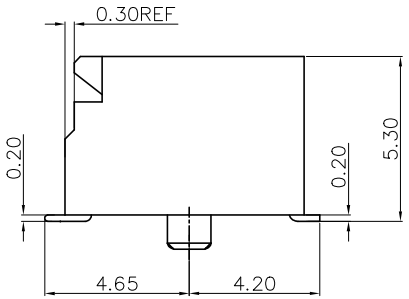
REVISION RECORD		
REV	DESCRIPTION	DRFT
10	A-release	Roy 11/12/2014

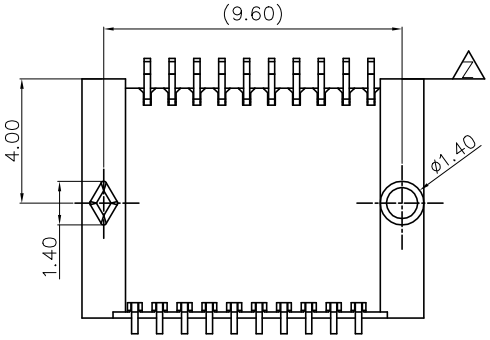


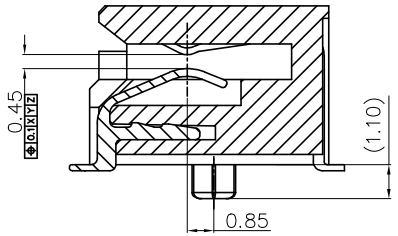




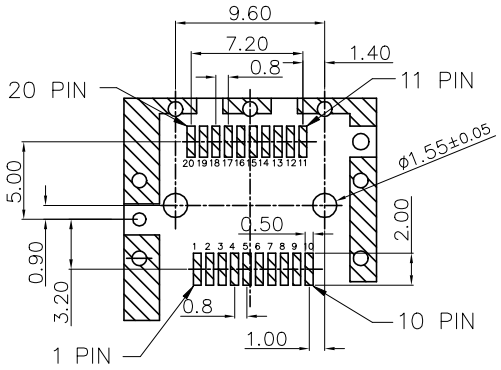


NOTE:
MATERIAL:
1. TERMINAL: COPPER ALLOY.
2. HOUSING: LCP UL 94V-0\BLACK.
PLATING:
1. 1.27um MIN. Ni UNDERPLATING.
2. 0.76um MIN. MATTE TIN PLATING ON SMT AREA.
3. 0.38um MIN. GOLD PLATING ON CONTACT AREA.
MECHANICAL:
1. DURABILITY: 100 CYCLES MIN.
2. INSERTION AND EXTRACTION FORCE: 40N MAX & 11.5N MAX.
ENVIRONMENTAL:
1. CONTACT RESISTANCE: 20 MILLIOHMS MAX INITIAL.
2. DIELECTRIC WITHSTANDING VOLTAGE: 300V AC/MIN.
3. OPERATION: -40°C~+85°C.
4. STORAGE: -55°C~+105°C.
5. REFLOW SOLDERING TEMPERATURE: 255°C~265°C(5~10 SECONDS).
6. ROHS COMPLIANT.





A-A SECTION



PC BOARD LAYOUT
COMPONENT SIDE SHOWN

MM (INCH)	DFTO Roy	DATE 10/08/2014	Pulse Electronics — RoHS Compliant
TOLERANCES EXCEPT AS NOTED	CHKD Victor	DATE 10/08/2014	
MM .0 ± 0.20 ± .00 ± 0.15 ± .000 ± 0.075 ±	APPVL Victor	DATE 10/08/2014	TITLE: SFP+ 1X1 CONNECTOR
ANGLES ± 0.5°	MATERIAL :		DRAWING NO. SFPPC-1000-L — SIZE A3 — REV 10
THIRD ANGLE PROJECTION	QT'Y :		/PART NO. SFPPC-1000-L
DETACHED LISTS	FINISH :		DO NOT SCALE DRAWING — SHEET 1 OF 1
	SCALE : 1:1		